

| Form PTO 1445 (Modified) | | U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | | ATTY DOCKET NO. 216932US2 | | SERIAL NO. New Application | |
|--|-----------------------|--|------|--------------------------------|--------------------|-------------------------------|----------------------------|
| LIST OF REFERENCES CITED BY APPLICANT | | APPLICANT | | Masaki YAMADA, et al. | | | |
| | | FILING DATE Herewith | | GROUP | | | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | FILING DATE IF APPROPRIATE |
| | AA | | | | | | |
| | AB | | | | | | |
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| FOREIGN PATENT DOCUMENTS | | | | | | | |
| | | DOCUMENT NUMBER | DATE | COUNTRY | TRANSLATION YES | NO | |
| | AO | | | | | | |
| | AP | | | | | | |
| | AQ | | | | | | |
| | AR | | | | | | |
| | AS | | | | | | |
| | AT | | | | | | |
| | AU | | | | | | |
| | AV | | | | | | |
| OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.) | | | | | | | |
| | AW | Y. MORAND, et al., "COPPER DUAL DAMASCENE INTEGRATION USING ORGANIC LOW K MATERIAL: CONSTRUCTION ARCHITECTURE COMPARISON", Proceedings of the International Interconnect Technology Conference, IEEE 2000, pgs. 225 - 227. | | | | | |
| | AX | H. KUDO, et al. "COPPER DUAL DAMASCENE INTERCONNECTS WITH VERY LOW-K DIELECTRICS TARGETING FOR 130 nm NODE", Proceedings of the International Interconnect Technology Conference, IEEE 2000, pgs. 270 - 272. | | | | | |
| | AY | | | | | | |
| | AZ | | | | | | |
| Examiner | <i>Debra B. Blake</i> | | | Date Considered <i>9/10/03</i> | | | |
| *Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |